**OmniCoat™**

Allows easy stripping of hard to remove photoresists and other materials plus improved adhesion

### FEATURES

- Easy, fast, clean & safe removal
- Uses existing strippers and processes
- Uses a very thin coating
- Applied by spin coating
- Adhesion Promoter

### BENEFITS

- Can now strip SU-8 & SU-8 2000. Reworks can be performed
- No highly dangerous wet chemistry or reactive gases required
- Minimizes or eliminates under plating
- No deposition layer required
- Improves adhesion to difficult substrates like Au, Cu and Quartz

Plated Nickel structure after removal of SU-8 using *OmniCoat™*

1) Coat and Bake *OmniCoat™* over seed layer
2) Coat and Bake SU-8 or SU-8 2000
3) Expose and Develop SU-8 or SU-8 2000
4) Develop (wet or dry) *OmniCoat™*
5) Plate metal
6) Strip resist in Remover PG
Processing Guidelines

COAT RELEASE LAYER:

Dynamic dispense: 1 - 4ml (depending on substrate diameter) of OmniCoat™
Spin: 500 rpm for 5 sec with acceleration of 100 R/s
3000 rpm for 30 sec with acceleration of 300 R/s

Note: For effective removal a thickness of no less than 17nm should be applied. Thicker coatings could be more effective depending on the substrate type

Bake: 200° C hotplate for 1 min; allow substrate to cool to room temperature

COAT, EXPOSE, PEB & DEVELOP SU-8 or SU8-2000:

Perform normal SU-8 processing according to the guidelines from datasheet.

DEVELOP OmniCoat™:

O₂ Plasma removal: Typical de-scum program
Power – 100 W
Flow Rate – 35,
Pressure – 190 mTorr
Time – 30 s

Wet removal: MCC 101 Developer: immersion with agitation; 1 min; DI rinse; 2min
Microposit MF 319: immersion with agitation; 30 sec; DI rinse; 2 min

Other developers can be used. The process must be adjusted for different developer formulations. It may be beneficial to perform a short O₂ plasma flash descum after wet development.

PLATE or OTHER PROCESSING

STRIP SU-8/ SU-8 2000:
Immersion in Remover PG (NMP) at 80°C for 30 min**. Ultrasonics may be required.
(**Depends on feature size and orientation. >5 um)